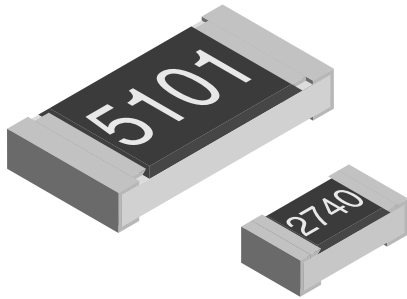




Thin Film Rectangular Chip Resistors



FEATURES

- Metal film layer on high quality ceramic
- Protective top coat
- Pure tin on nickel barrier layer
- Low temperature coefficient and tight tolerances
- 56 days at 40 °C and 93 % relative humidity down to $\leq \pm 0.2$ %
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT

TECHNICAL SPECIFICATIONS				
DESCRIPTION	M10	M11	M12	M25
Imperial size	0402	0603	0805	1206
Metric size code	RR1005M	RR1608M	RR2012M	RR3216M
Resistance range	10 Ω to 20 k Ω	10 Ω to 56 k Ω	10 Ω to 100 k Ω	10 Ω to 220 k Ω
Resistance tolerance	± 1 %; ± 0.5 %	± 1 %; ± 0.5 %; ± 0.25 %; ± 0.1 %		
Temperature coefficient	± 50 ppm/K; ± 25 ppm/K			
Rated dissipation, P_{70}	0.063 W	0.100 W	0.125 W	0.250 W
Operating voltage, $U_{max. AC/RMS/DC}$	25 V	75 V	150 V	200 V
Permissible film temperature, $\vartheta_{F max.}$	125 °C (155 °C)			
Operating temperature range	-55 °C to 125 °C (155 °C)			
Insulation voltage: 1 min; U_{ins}	> 50 V	> 100 V	> 200 V	> 300 V
Failure rate: FIT _{observed}	0.3×10^{-9} /h			

Notes

- Power rating depends on the max. temperature at the solder point, the component placement density and the substrate material
- Marking: 4 digits, M10 - no marking

MAXIMUM RESISTANCE CHANGE AT RATED DISSIPATION		
OPERATION MODE		STANDARD
Rated dissipation, P_{70}	M10	0.063 W
	M11	0.100 W
	M12	0.125 W
	M25	0.250 W
Operating temperature range	-55 °C to 125 °C (155 °C)	
Permissible film temperature, $\vartheta_{F max.}$	125 °C (155 °C)	
Max. resistance change at P_{70} for resistance range, $ \Delta R/R $, after:	M10	10 Ω to 20 k Ω
	M11	10 Ω to 56 k Ω
	M12	10 Ω to 100 k Ω
	M25	10 Ω to 220 k Ω
	1000 h	≤ 0.2 %

Note

- A suitable low thermal resistance of the circuit board assembly must be safeguarded in order to maintain the film temperature of the resistors within the specified limits. Please consider the application note "Thermal Management in Surface-Mounted Resistor Applications" (www.vishay.com/doc?228844) for information on the general nature of thermal resistance.



www.vishay.com

Not for New Designs. Alternative Device: TNPW e3

M10, M11, M12, M25

Vishay Draloric

TEMPERATURE COEFFICIENT AND RESISTANCE RANGE				
TYPE	TCR	TOLERANCE	RESISTANCE	E-SERIES
M10	± 25 ppm/K	± 0.5 %	10 Ω to 20 kΩ	E24; E96
M11	± 50 ppm/K	± 0.5 %	10 Ω to 56 kΩ	
		± 0.1 %		
	± 25 ppm/K	± 1 %		
		± 0.5 %		
M12	± 50 ppm/K	± 0.1 %	10 Ω to 100 kΩ	
		± 0.5 %		
		± 0.25 %		
M25	± 25 ppm/K	± 0.1 %	10 Ω to 220 kΩ	
		± 1 %		
		± 0.5 %		
	± 0.1 %			

PACKAGING						
TYPE	CODE	QUANTITY	PACKAGING STYLE	WIDTH	PITCH	PACKAGING DIMENSIONS
M10	P0	10 000	Paper tape according to IEC 60286-3, Type 1a	8 mm	2 mm	Ø 180 mm/7"
	PZ	50 000				Ø 330 mm/13"
M11 M12 M25	P1	1000 ⁽¹⁾			4 mm	Ø 180 mm/7"
	P5	5000				Ø 180 mm/7"
	PN	20 000				Ø 330 mm/13"

Note

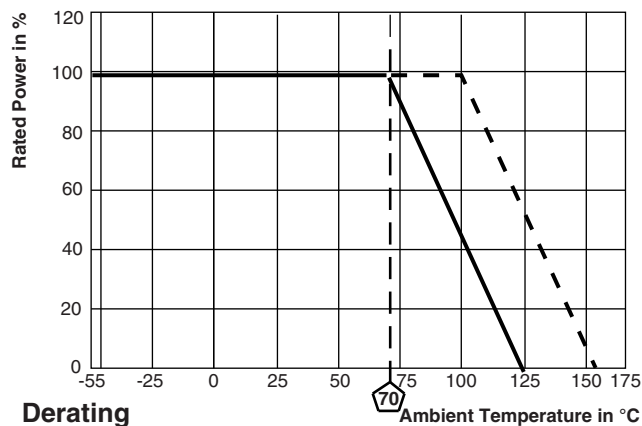
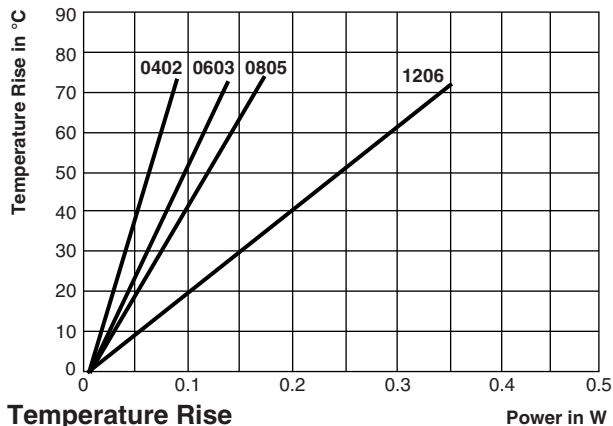
⁽¹⁾ For TCR ≤ 25 ppm/K and tolerance ≤ 0.1 % only



PART NUMBER AND PRODUCT DESCRIPTION																	
PART NUMBER: M1004020D5620DP000																	
M	1	0	0	4	0	2	0	D	5	6	2	0	D	P	0	0	0
TYPE / SIZE		VERSION			TCR		RESISTANCE			TOLERANCE			PACKAGING				
M100402 M110603 M120805 M251206		0 = neutral			D = ± 25 ppm/K C = ± 50 ppm/K		3 digit value 1 digit multiplier Multiplier 8 = $\times 10^{-2}$ 9 = $\times 10^{-1}$ 0 = $\times 10^0$ 1 = $\times 10^1$ 2 = $\times 10^2$ 3 = $\times 10^3$			B = ± 0.1 % C = ± 0.25 % D = ± 0.5 % F = ± 1 %			P0 P1 P5 PN PZ				
PRODUCT DESCRIPTION: M10 25 562R 0.5 % P0																	
M10		25			562R		0.5 %			P0							
TYPE		TCR			RESISTANCE		TOLERANCE			PACKAGING							
M10 M11 M12 M25		± 25 ppm/K ± 50 ppm/K			49K9 = 49.9 k Ω 5R1 = 5.1 Ω		± 0.1 % ± 0.25 % ± 0.5 % ± 1 %			P0 P1 P5 PN PZ							

Note

- Products can be ordered using either the PART NUMBER or the PRODUCT DESCRIPTION



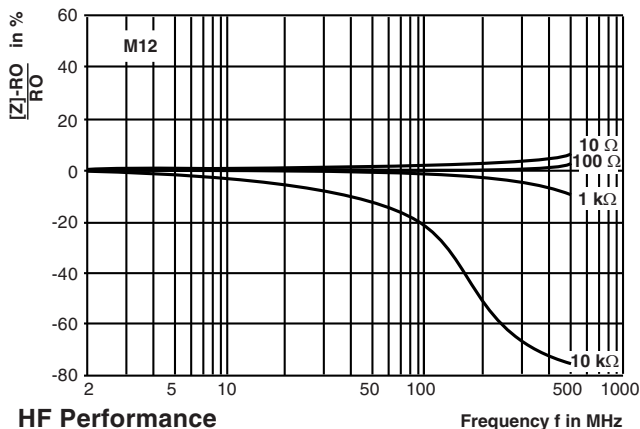
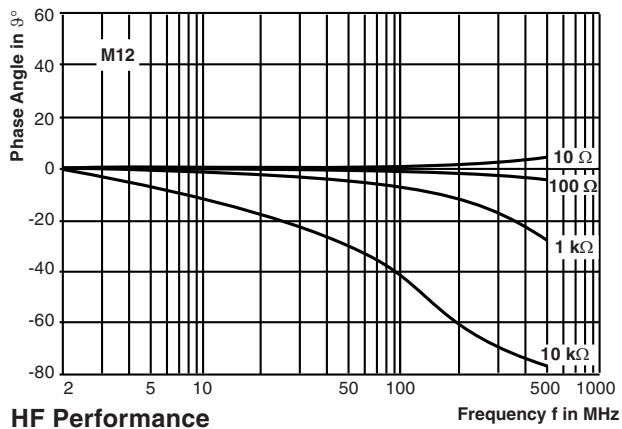
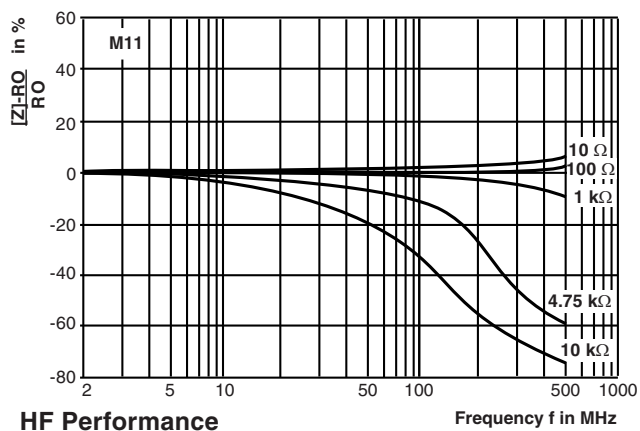
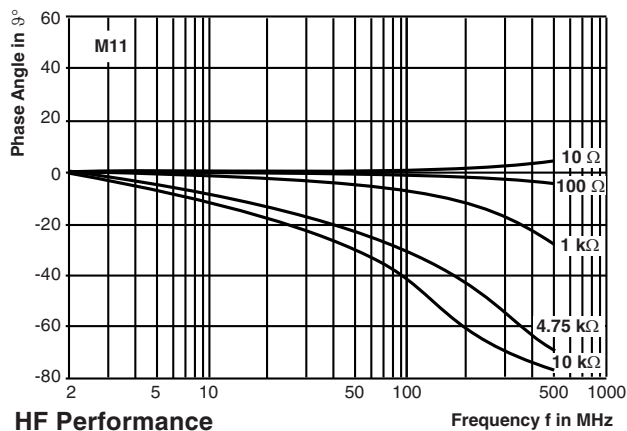
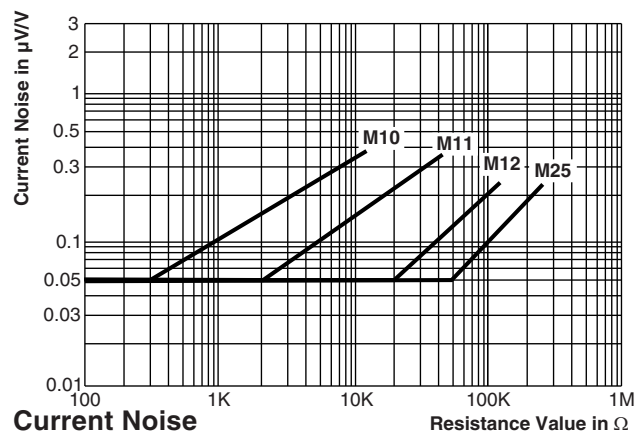
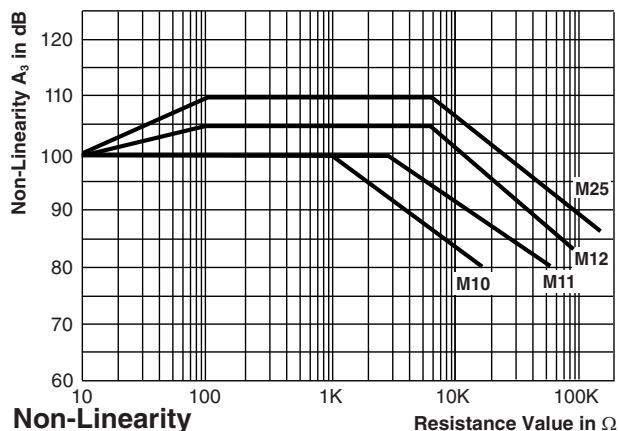
Note

- The solid line is based on IEC / EN reference test conditions which is considered as standard mode. However, above that the maximum permissible film temperature is 155 °C (dashed line).



M10, M11, M12, M25

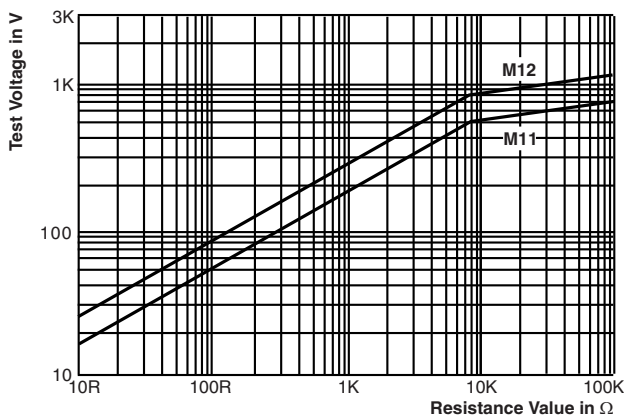
Vishay Draloric



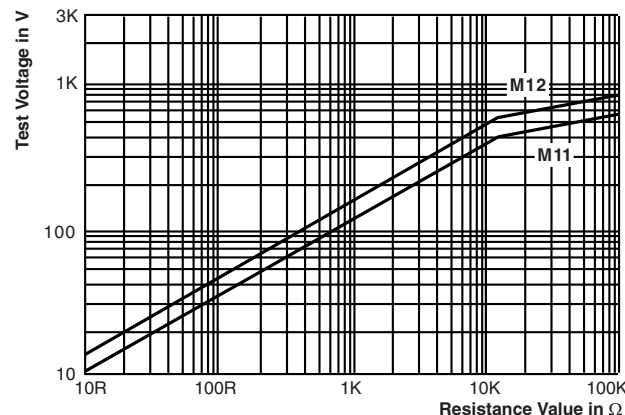


M10, M11, M12, M25

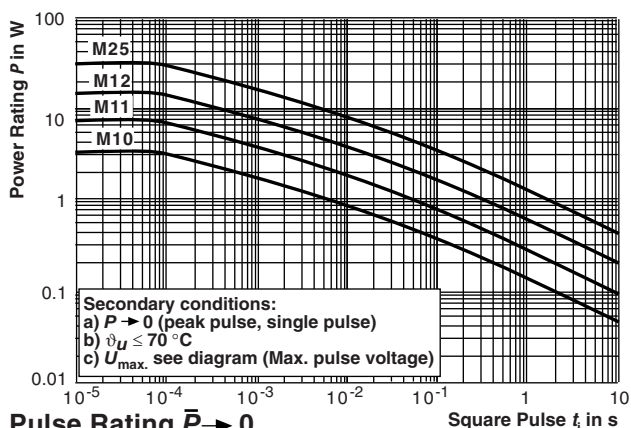
Vishay Draloric



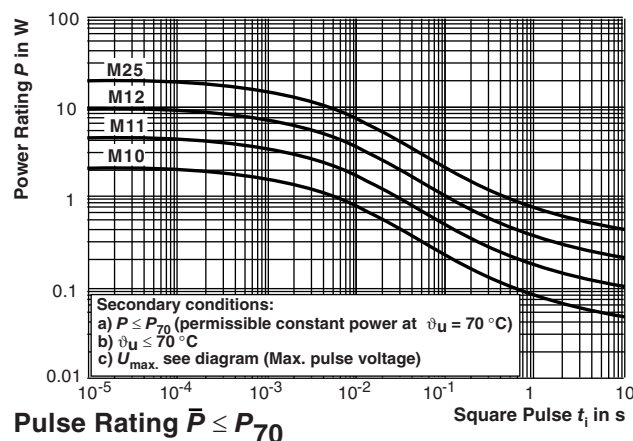
Single-Pulse High Voltage Overload Test
1.2/50 μs EN140000 4.27



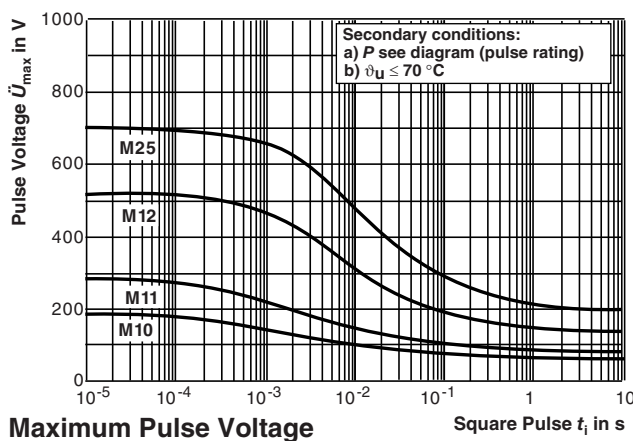
Single-Pulse High Voltage Overload Test
10/700 μs EN140000 4.27



Pulse Rating $\bar{P} \rightarrow 0$



Pulse Rating $\bar{P} \leq P_{70}$



Maximum Pulse Voltage

**DESCRIPTION**

Production is strictly controlled and follows an extensive set of instructions established for reproducibility. A homogeneous film of special metal alloy is deposited on a high grade ceramic substrate (Al_2O_3) and conditioned to achieve the desired temperature coefficient. Specially designed inner contacts are deposited on both sides. A special laser is used to achieve the target value by smoothly fine trimming the resistive layer without damaging the ceramics. A further conditioning is applied in order to stabilize the trimming result. The resistor elements are covered by a protective coating designed for electrical, mechanical and climatic protection. The terminations receive a final pure tin on nickel plating.

The result of the determined production is verified by an extensive testing procedure and optical inspection performed on 100 % of the individual chip resistors. This includes full screening for the elimination of products with a potential risk of early life failures according to EN 140401-801, 2.1.2.2. Only accepted products are laid directly into the tape in accordance with **IEC 60286-3, Type 1a** ⁽¹⁾.

ASSEMBLY

The resistors are suitable for processing on automatic SMD assembly systems. They are suitable for automatic soldering using wave, reflow or vapor phase as shown in **IEC 61760-1** ⁽¹⁾. The encapsulation is resistant to all cleaning solvents commonly used in the electronics industry, including alcohols, esters and aqueous solutions. The suitability of conformal coatings, potting compounds and their processes, if applied, shall be qualified by appropriate means to ensure the long-term stability of the whole system.

The resistors are RoHS-compliant, the pure tin plating provides compatibility with lead (Pb)-free and lead-containing soldering processes. The immunity of the plating against tin whisker growth has been proven under extensive testing.

MATERIALS

Vishay acknowledges the following systems for the regulation of hazardous substances:

- IEC 62474, Material Declaration for Products of and for the Electrotechnical Industry, with the list of declarable substances given therein ⁽²⁾
- The Global Automotive Declarable Substance List (GADSL) ⁽³⁾
- The REACH regulation (1907/2006/EC) and the related list of substances with very high concern (SVHC) ⁽⁴⁾ for its supply chain

The products do not contain any of the banned substances as per IEC 62474, GADSL, or the SVHC list, see www.vishay.com/how/leadfree.

Hence the products fully comply with the following directives:

- 2000/53/EC End-of-Life Vehicle Directive (ELV) and Annex II (ELV II)
- 2011/65/EU Restriction of the Use of Hazardous Substances Directive (RoHS) with amendment 2015/863/EU
- 2012/19/EU Waste Electrical and Electronic Equipment Directive (WEEE)

Vishay pursues the elimination of conflict minerals from its supply chain, see the Conflict Minerals Policy at www.vishay.com/doc?49037.

RELATED PRODUCTS

The M10, M11, M12, M25 series are not recommended for new designs. A suitable replacement for new designs is the TNPW e3 series which has advanced performance and extended range availability. Please refer to the latest edition of the TNPW e3 data sheet: www.vishay.com/doc?28758.

Notes

- ⁽¹⁾ The quoted IEC standards are also released as EN standards with the same number and identical contents.
- ⁽²⁾ The IEC 62474 list of declarable substances is maintained in a dedicated database, which is available at <http://std.iec.ch/iec62474>.
- ⁽³⁾ The Global Automotive Declarable Substance List (GADSL) is maintained by the American Chemistry Council and available at www.gadsl.org.
- ⁽⁴⁾ The SVHC list is maintained by the European Chemical Agency (ECHA) and available at <http://echa.europa.eu/candidate-list-table>.



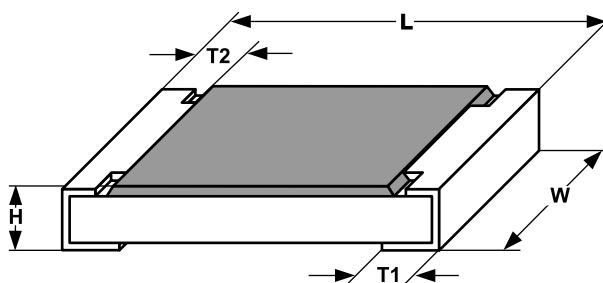
TEST PROCEDURES AND REQUIREMENTS				
EN 60115-1 CLAUSE	IEC 60068-2 ⁽¹⁾ TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)
			Stability for product types:	
			M10	10 Ω o 20 k Ω
			M11	10 Ω to 56 k Ω
			M12	10 Ω to 100 k Ω
			M25	10 Ω to 220 k Ω
4.5	-	Resistance	-	$\pm 1.0 \% R$; $\pm 0.5 \% R$; $\pm 0.25 \% R$; $\pm 0.1 \% R$
4.8	-	Temperature coefficient	At (20/-55/20) °C and (20/125/20) °C	± 50 ppm/K; ± 25 ppm/K
4.25.1	-	Endurance at 70 °C: standard operation mode	$U = \sqrt{P_{70}} \times \bar{R} \leq U_{max.}$; whichever is the less severe; 1.5 h on; 0.5 h off; 70 °C; 1000 h	$\pm 0.2 \% R$
4.25.3	-	Endurance at upper category temperature	125 °C; 1000 h	$\pm 0.2 \% R$
4.24	78 (Cab)	Damp heat, steady state	(40 \pm 2) °C; 56 days; (93 \pm 3) % RH	$\pm 0.2 \% R$
4.19	14 (Na)	Rapid change of temperature	30 min at LCT; 30 min at UCT; LCT = -55 °C; UCT = 125 °C	$\pm 0.05 \% R$
4.13	-	Short time overload	$U = 2.5 \times \sqrt{P_{70}} \times \bar{R} \leq 2 \times U_{max.}$; 2 s	$\pm 0.05 \% R$
4.18	58 (Td)	Resistance to soldering heat	Solder bath method; (260 \pm 5) °C; (10 \pm 1) s	$\pm 0.05 \% R$

Note

⁽¹⁾ The quoted IEC standards are also released as EN standards with the same number and identical contents.

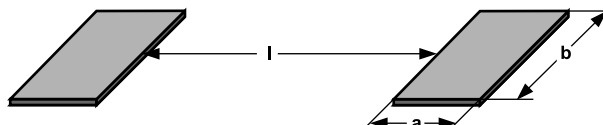


DIMENSIONS



DIMENSIONS AND MASS						
TYPE	H (mm)	L (mm)	W (mm)	T1 (mm)	T2 (mm)	MASS (mg)
M10	0.35 ± 0.05	1.00 ± 0.05	0.50 ± 0.05	0.25 ± 0.1	0.20 ± 0.1	0.65
M11	0.45 ± 0.05	1.55 + 0.1 / - 0.05	0.85 ± 0.1	0.30 ± 0.2	0.30 ± 0.2	2
M12	0.45 ± 0.05	2.00 + 0.2 / - 0.1	1.25 ± 0.15	0.30 + 0.2 / - 0.1	0.30 ± 0.2	5.5
M25	0.55 ± 0.05	3.20 + 0.1 / - 0.2	1.60 ± 0.15	0.45 ± 0.2	0.40 ± 0.2	10

SOLDER PAD DIMENSIONS



RECOMMENDED SOLDER PAD DIMENSIONS						
TYPE	WAVE SOLDERING			REFLOW SOLDERING		
	a (mm)	b (mm)	l (mm)	a (mm)	b (mm)	l (mm)
M10	-	-	-	0.40	0.60	0.50
M11	0.90	0.90	1.00	0.50	0.90	1.00
M12	0.90	1.30	1.30	0.70	1.40	1.20
M25	1.10	1.70	2.30	0.90	1.70	2.00

Notes

- The given solder pad dimensions reflect the considerations for board design and assembly as outlined e.g. in standards IEC 61188-5-x ⁽¹⁾, or in publication IPC-7351. They do not guarantee any supposed thermal properties, particularly as these are also strongly influenced by many other parameters. Still, the given solder pad dimensions will be found adequate for most general applications.
- (1) The quoted IEC standards are also released as EN standards with the same number and identical contents



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Material Category Policy

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.